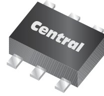
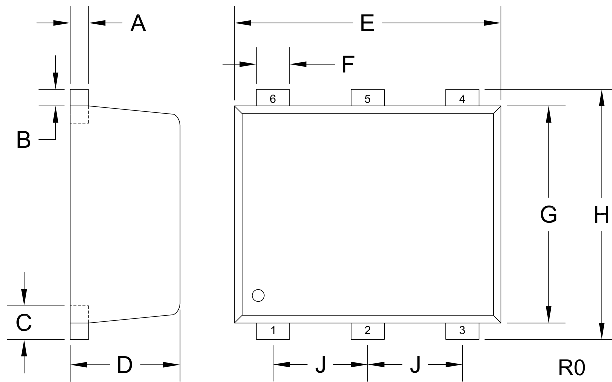
Package Details

SOT-963 Case



Mechanical Drawing



SYMBOL	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	0.002	0.006	0.050	0.150
B	0.002	0.006	0.050	0.150
C	0.005	0.007	0.125	0.175
D	0.016	0.020	0.400	0.500
E	0.037	0.041	0.950	1.050
F	0.004	0.008	0.100	0.200
G	0.030	0.033	0.750	0.850
H	0.037	0.041	0.950	1.050
J	0.014		0.350	

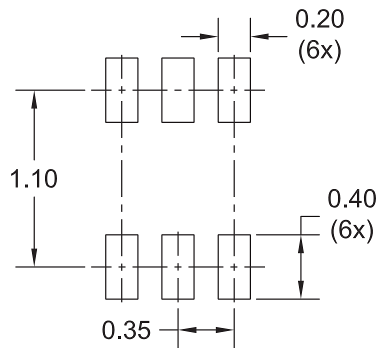
DIMENSIONS

SOT-963 (REV: R0)

Lead Code:
Reference individual device datasheet.

Part Marking: 2-3 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



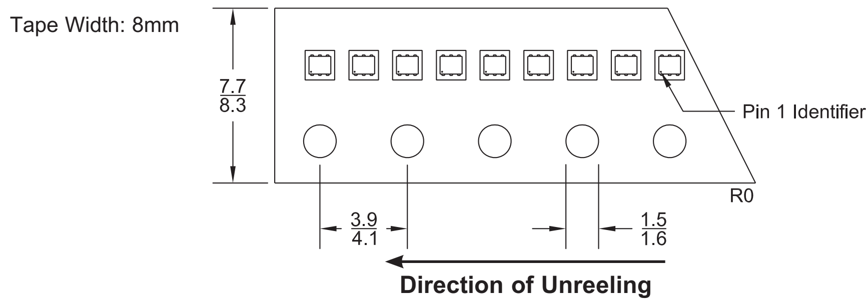
R0

R1 (4-March 2010)

Package Details

SOT-963 Case

Tape Dimensions and Orientation (Dimensions in mm)



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

Packaging Base

7” Reel = 8,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	72,000	9x9x5	23x23x13	3	2
	18	144,000	9x9x9	23x23x23	6	3
	40	320,000	21x9x9	53x23x23	13	6
	108	864,000	27x9x17	69x23x43	34	16

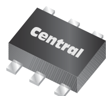
Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R1 (4-March 2010)

Material Composition Specification

SOT-963 Case



Device average mass . . . . **1.195 mg**
Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.51%	0.03	Si	7440-21-3	2.51%	0.03	25,109
bond wire	gold	1.26%	0.015	Au	7440-57-5	1.26%	0.015	12,554
leadframe	Cu alloy	42.87%	0.5122	Cu	7440-50-8	41.93%	0.501	419,317
				Fe	7439-89-6	0.92%	0.011	9,207
				P	7723-14-0	0.01%	0.0001	84
				Zn	7440-66-6	0.01%	0.0001	84
die attach	silver epoxy	1.17%	0.014	Ag	7440-22-4	1.0%	0.012	10,044
				resin filler	Proprietary	0.17%	0.002	1,674
encapsulation	EMC	50.8%	0.607	amorphous silica	7631-86-9	49.21%	0.588	492,133
				epoxy resin	Proprietary	1.51%	0.018	15,065
				carbon	1333-86-4	0.08%	0.001	837
plating	Ni/Pd/Au	1.39%	0.0166	Ni	7440-02-0	1.34%	0.016	13,391
				Pd	7440-05-3	0.01%	0.0001	84
				Au	7440-57-5	0.04%	0.0005	418

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.